2SA0886 (2SA886)

Silicon PNP epitaxial planar type

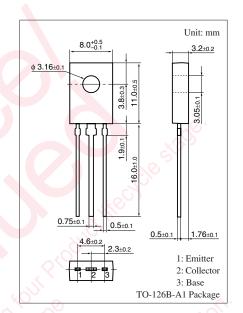
For low-frequency power amplification Complementary to 2SC1847

■ Features

- Output of 4 W can be obtained by a complementary pair with 2SC1847
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	-50	V	
Collector-emitter voltage (Base open)	V _{CEO}	-40	V	
Emitter-base voltage (Collector open)	V_{EBO}	-5	V	
Collector current	I_{C}	-1.5	A	
Peak collector current	I_{CP}	-3	A	
Collector power dissipation	P _C	1.2	W	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

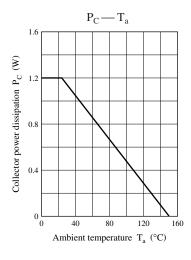
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = -1 \text{ mA}, I_E = 0$	-50	250		V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2 \text{ mA}, I_B = 0$	-40	, O		V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20 \text{ V}, I_E = 0$	7.9		-1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10 \text{ V}, I_B = 0$			-100	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-10	μΑ
Forward current transfer ratio *	h_{FE}	$V_{CE} = -5 \text{ V}, I_{C} = -1 \text{ A}$	80		220	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -1.5 \text{ A}, I_B = -0.15 \text{ A}$			-1.0	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = -2 A, I_B = -0.2 A$			-1.5	V
Transition frequency	f_T	$V_{CB} = -5 \text{ V}, I_E = 0.5 \text{ A}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		45		pF

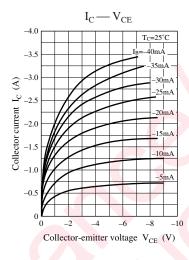
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

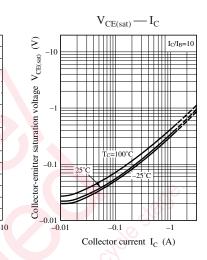
2. *: Rank classification

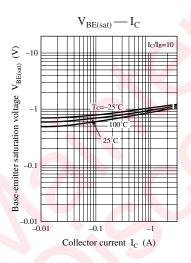
Rank	Q	R		
$h_{\rm FE1}$	80 to 160	120 to 220		

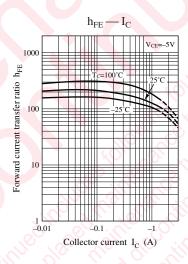
Note) The part numbers in the parenthesis show conventional part number.

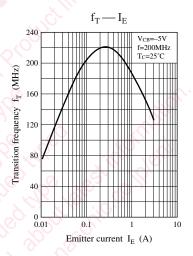


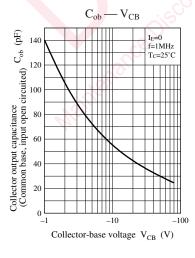


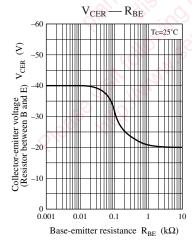


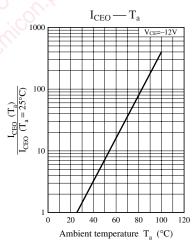




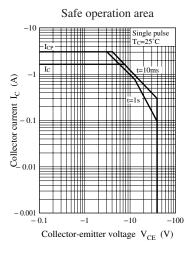


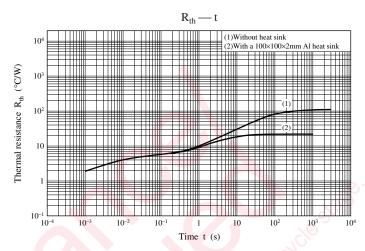






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